PCN# 20260223007.1
Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request

Date: February 24, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ADS8695IPW	595-ADS8695IPW
OPA4191IPWT	NULL
INA819IDR	NULL
OPA1612AID	OPA1612AID
ISOW1432DFMR	NULL
ADS8689IPWR	NULL
SN74LVC245ANS	NULL
OPA191ID	NULL
CDCE949PW	CDCE949PW
OPA141AID	OPA141AID
TLV2379IDR	NULL
ADS8685IPW	ADS8685IPW
INA821IDR	NULL
OPA4317ID	NULL
ISOW7741DFMR	595-ISOW7741DFMR
TLV320DAC3100IRHBR	TLV320DAC3100IRHBR
OPA1688ID	OPA1688ID
OPA171AIDR	NULL
ADS8354IPWR	ADS8354IPWR
OPA209AID	OPA209AID
ISOW7742DFMR	NULL
ADS7254IPW	ADS7254IPW
TLV2316IDR	NULL
ADS7853IPW	ADS7853IPW
OPA2187IDR	NULL
ADS1262IPW	ADS1262IPW
ISOW1044BDFMR	NULL
CDCS502PW	CDCS502PW
OPA4196ID	NULL
DAC60004IPW	DAC60004IPW
ADS112C04IPWR	NULL
ADS8661IPWR	595-ADS8661IPWR
ISOW7721FDFMR	NULL
TLV4171IDR	NULL
OPA1654AIPWR	NULL
ADS8691IPWR	ADS8691IPWR
ADS8665IPWR	NULL
ADS1119IPWR	ADS1119IPWR
MUX509IPWR	MUX509IPWR
OPA4180IDR	OPA4180IDR
OPA4197IDR	NULL
CDCE925PW	CDCE925PW
TLV2376IDR	NULL
CDCE913PWR	CDCE913PWR
ISOW1432BDFMR	NULL
INA818IDR	NULL
ADS8671IPW	ADS8671IPW

ADS8691IPW	ADS8691IPW
OPA2210IDR	NULL
MUX36S08IPWR	MUX36S08IPWR
OPA4191ID	NULL
TLV171IDR	TLV171IDR
INA828ID	NULL
TLV376IDR	TLV376IDR
ADS8665IPW	NULL
TLV2171IDGKR	595-TLV2171IDGKR
ADS8681IPWR	NULL
OPA2172ID	OPA2172ID
OPA4191IPWR	NULL
INA1650IPW	NULL
ADS8675IPW	ADS8675IPW
ADS8695IPW	ADS8695IPW
OPA4191IDR	NULL
OPA4316IPWR	NULL
OPA172IDR	OPA172IDR
OPA2187ID	NULL
REF5010AIDR	REF5010AIDR
CDCS502PWR	CDCS502PWR
OPA170AID	NULL
ADS8689IPW	ADS8689IPW
DAC60004IPWR	DAC60004IPWR
TLV4316IPWR	NULL
CDCEL913PW	CDCEL913PW
OPA1688IDR	OPA1688IDR
ADS122U04IPWR	NULL
TLV4170IDR	NULL
ISOW1412DFMR	NULL
OPA2191IDR	NULL
OPA2172IDR	OPA2172IDR
OPA2192IDR	OPA2192IDR
REF5045AIDR	REF5045AIDR
MUX36D04IPW	MUX36D04IPW
OPA828ID	NULL
OPA145IDR	NULL
OPA202IDR	OPA202IDR
OPA4192IDR	OPA4192IDR
OPA2192ID	OPA2192ID
OPA2197IDR	OPA2197IDR
OPA4140AIDR	NULL
ISOW7744DFMR	NULL
CDCE937PWR	CDCE937PWR
THS4531AID	THS4531AID
MUX508IPW	MUX508IPW
INA1651IPW	NULL
TLV320DAC3100IRHBT	TLV320DAC3100IRHBT
TLV320AIC3110IRHBT	TLV320AIC3110IRHBT
ADS7253IPW	ADS7253IPW
OPA2320AID	OPA2320AID
TLV4313IPWR	TLV4313IPWR
ADS7854IPW	ADS7854IPW
CDCEL913PWR	595-CDCEL913PWR
MUX36D04IPWR	NULL
OPA197ID	OPA197ID
LM384N/NOPB	LM384N/NOPB
ADS122C04IPWR	NULL

TLV2171IDGKR	TLV2171IDGKR
OPA2320AIDR	OPA2320AIDR
DAC80004IPW	DAC80004IPW
DRV110APWR	DRV110APWR
ISOW7740FDFMR	NULL
OPA192IDR	OPA192IDR
INA1651IPWR	NULL
ISOW1412BDFMR	NULL
SN74LVC541ANSR	SN74LVC541ANSR
ADS1262IPWR	NULL
ADS8661IPW	NULL
OPA145ID	NULL
CDCE913PWG4	CDCE913PW
INA848ID	NULL
CDCE925PWR	CDCE925PWR
ADS1219IPWR	NULL
INA1650IPWR	NULL
OPA2316ID	OPA2316ID
SN74LVCH245ADBR	NULL
ISOW7742FDFMR	NULL
TMUX8108PWR	NULL
TLV2172IDR	NULL
OPA188AID	OPA188AID
OPA188AIDR	OPA188AIDR
OPA1612AIDR	OPA1612AIDR
OPA4316IPW	OPA4316IPW
SN74LVC245ANSR	NULL
CDCE913PW	CDCE913PW
OPA191IDR	OPA191IDR
OPA2197ID	OPA2197ID
SN74LVC541ADBR	SN74LVC541ADBR
ADS8685IPWR	NULL
SN74LVC2244ANSR	SN74LVC2244ANSR
CDCS503PWR	CDCS503PWR
OPA4196IDR	NULL
TLV2171IDR	TLV2171IDR
TLV4333IDR	NULL
OPA197IDR	OPA197IDR
INA828IDR	NULL
OPA4197ID	NULL
OPA196ID	NULL
INA188IDR	NULL
ISOW7721DFMR	NULL
OPA4140AID	OPA4140AID
DAC70004IPW	DAC70004IPW
CDCEL913PWR	CDCEL913PWR
INA818ID	NULL
OPA828IDR	NULL
ISOW1044DFMR	NULL
LM380N/NOPB	NULL
TLV4172IDR	NULL
MUX509IPW	MUX509IPW

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260223007.1		PCN Date:	February 24, 2026
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)			
Customer Contact:	Change Management team	Dept:	Quality Services	
Proposed 1st Ship Date:	May 25, 2026	Estimated Sample Availability:	April 25, 2026	

*Sample requests received after April 25, 2026 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of new assembly material set to add Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and piece part changes as follows:

Group 1

Material	Current	Proposed
Wire diam/type	0.96mil Au + 0.8mil Cu	0.8mil Cu

Group 2

Material	Current	Proposed
Wire diam/type	0.8mil Au, 0.96mil Au	0.8mil Cu

Group 3

Material	Current	Proposed
Wire diam/type	0.90mil Au, 0.96mil Au, 1.18mil Au	0.96mil Cu

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Group 1 Product Affected:

ISOW1044BDFMR	ISOW7721FDFMR	ISOW7742DFMR	
ISOW1044DFMR	ISOW7740DFMR	ISOW7742FDFMR	
ISOW1412BDFMR	ISOW7740FDFMR	ISOW7743DFMR	
ISOW1412DFMR	ISOW7741BDFMR	ISOW7743FDFMR	
ISOW1432BDFMR	ISOW7741DFMR	ISOW7744DFMR	
ISOW1432DFMR	ISOW7741FBDFMR	ISOW7744FDFMR	
ISOW7721DFMR	ISOW7741FDFMR		

Group 2 Product Affected:

ADS5281IRGCR	CDCE937PWR	CDCS502PWR	
ADS5281IRGCT	CDCE937PWRG4	CDCS503PW	
ADS5282IRGCR	CDCE937R01PWR	CDCS503PWR	
ADS5282IRGCT	CDCE937R02PWR	SN1002030RGZR	
CDC734PWR	CDCE937R04PWR	SN1301027IRGCT	
CDCE913PW	CDCE937R07PWR	SN74ABT646ANSR	
CDCE913PWG4	CDCE949PW	SN74ALVC245NSR	
CDCE913PWR	CDCE949PWG4	SN74CBTLV3861NSR	
CDCE913PWRG4	CDCE949PWR	SN74LVC2244ANSR	
CDCE913R01PWR	CDCE949R03PWR	SN74LVC245ANS	
CDCE913R02PWR	CDCE949R04PWR	SN74LVC245ANSR	
CDCE913R05PWR	CDCE949R05PWR	SN74LVC541ANS	
CDCE913R07PWR	CDCEL824PWR	SN74LVCC3245ANSR	
CDCE913R08PWR	CDCEL913PW	SN74LVCC4245ANS	
CDCE913R09PWR	CDCEL913PWR	SN74LVCC4245ANSR	
CDCE913R0APWR	CDCEL925PW	SN74LVCH245ANSR	
CDCE913R0BPWR	CDCEL925PWR	SNB6006PW-P	
CDCE913R0CPWR	CDCEL937PW	SNB6006PWR-P	
CDCE925PW	CDCEL937PWR	TLV320AIC3110IRHBT	
CDCE925PWG4	CDCEL937R08PWR	TLV320DAC3100IRHBR	
CDCE925PWR	CDCEL937R09PWR	TLV320DAC3100IRHBT	
CDCE925R01PWR	CDCEL949PW	TLV320DAC3101IRHBT	
CDCE925R02PWR	CDCEL949PWR	TLV320DAC3120IRHBT	
CDCE925R04PWR	CDCS501PW	TUSB3410IRHBT	
CDCE937PW	CDCS501PWR	TUSB3410RHBT	
CDCE937PWG4	CDCS502PW		

Group 3 Product Affected:

74AVC16T245DGGR-P	INA828ID	OPA4172IDR	
74LVCH16245ADGGRG4	INA828IDR	OPA4180ID	
ADS1119IPW	INA848ID	OPA4180IDR	
ADS1119IPWR	INA848IDR	OPA4191ID	
ADS1119IPWT	LM380N/NOPB	OPA4191IDR	
ADS112C04IPW	LM384N/NOPB	OPA4191IPWR	
ADS112C04IPWR	MSP430V303IRHAR	OPA4191IPWT	
ADS112U04IPW	MSP430V331IRHAR	OPA4192ID	
ADS112U04IPWR	MSP430V424IRHAR	OPA4192IDR	

ADS1219IPW	MUX36D04IPW	OPA4196ID	
ADS1219IPWR	MUX36D04IPWR	OPA4196IDR	
ADS1219IPWT	MUX36S08IPW	OPA4197ID	
ADS122C04IPW	MUX36S08IPWR	OPA4197IDR	
ADS122C04IPWR	MUX508IPW	OPA4316IPW	
ADS122U04IPW	MUX508IPWR	OPA4316IPWR	
ADS122U04IPWR	MUX508IWPWR	OPA4317ID	
ADS1262IPW	MUX509IPW	OPA4317IDR	
ADS1262IPWR	MUX509IPWR	OPA828ID	
ADS7253IPW	MUX509IWPWR	OPA828IDR	
ADS7253IPWR	OPA140AID	PSN07069A0PWR	
ADS7254IPW	OPA141AID	REF5010AIDR	
ADS7254IPWR	OPA141AIDR	REF5020AID	
ADS7853IPW	OPA145ID	REF5020AIDR	
ADS7853IPWR	OPA145IDR	REF5045AIDR	
ADS7854IPW	OPA1612AID	SN07069PWR	
ADS7854IPWR	OPA1612AIDR	SN1272DR	
ADS8353IPW	OPA1654AIPW	SN74ALVCF162834DL	
ADS8353IPWR	OPA1654AIPWR	SN74AVCH20T245GR	
ADS8354IPW	OPA1679IPWR	SN74LVC541ADB	
ADS8354IPWR	OPA1688ID	SN74LVC541ADBR	
ADS8661IPW	OPA1688IDR	SN74LVC541ANSR	
ADS8661IPWR	OPA170AID	SN74LVCH16245ADGG	
ADS8665IPW	OPA171AID	SN74LVCH16245AG-P	
ADS8665IPWR	OPA171AIDR	SN74LVCH245ADBR	
ADS8671IPW	OPA172ID	SN74LVTH373NSR	
ADS8671IPWR	OPA172IDR	SN74LVTH574NSR	
ADS8675IPW	OPA180ID	THS4531AID	
ADS8675IPWR	OPA180IDR	THS4531AIDR	
ADS8681IPW	OPA188AID	TLV170IDR	
ADS8681IPWR	OPA188AIDR	TLV171IDR	
ADS8685IPW	OPA191ID	TLV172IDR	
ADS8685IPWR	OPA191IDR	TLV2170IDR	
ADS8689IPW	OPA192ID	TLV2171IDGKR	
ADS8689IPWR	OPA192IDR	TLV2171IDGKT	
ADS8691IPW	OPA196ID	TLV2171IDR	
ADS8691IPWR	OPA196IDR	TLV2172IDR	
ADS8695IPW	OPA197ID	TLV2316IDR	
ADS8695IPWR	OPA197IDR	TLV2376IDR	
ADS8699IPW	OPA202ID	TLV2379IDR	
ADS8699IPWR	OPA202IDR	TLV333IDR	
AVC16T245DGGR-D	OPA209AID	TLV3502AID	
CC1070RGWR	OPA2172ID	TLV3502AIDG4	
CC1070RGWT	OPA2172IDR	TLV3502AIDR	
DAC60004IPW	OPA2187ID	TLV376IDR	

DAC60004IPWR	OPA2187IDR	TLV4170ID
DAC70004IPW	OPA2191ID	TLV4170IDR
DAC70004IPWR	OPA2191IDR	TLV4171ID
DAC80004IPW	OPA2192ID	TLV4171IDR
DAC80004IPWR	OPA2192IDR	TLV4172IDR
DRV110APWR	OPA2196ID	TLV4313IPWR
INA1650IPW	OPA2197ID	TLV4316IPWR
INA1650IPWR	OPA2197IDR	TLV4333IDR
INA1651IPW	OPA2210ID	TLV4379IPWR
INA1651IPWR	OPA2210IDR	TMUX8108PWR
INA188ID	OPA2316ID	TPS659101A1RSLR
INA188IDR	OPA2316IDR	TPS6591023A1RSLR
INA818ID	OPA2320AID	TPS6591023A1RSLT
INA818IDR	OPA2320AIDR	TPS65910A1RSLR-P
INA819ID	OPA2322AID	TPS65910A3A1RSL
INA819IDR	OPA4140AID	TPS65910A3A1RSLR
INA821ID	OPA4140AIDR	TPS65910AA1RSLR
INA821IDR	OPA4172ID	

Group 1 Qualification Report
Automotive New Product Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
Approve Date 07-May-2025

Product Attributes

Attributes	Qual Device: ISOW7741QDFMRQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Package Reference: AMC1305M25QDWQ1	QBS Package Reference: AMC131M03QDFMRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Power Management	Interface	Signal Chain	Signal Chain
Wafer Fab Supplier	FR-BIP-1, DMOS6, MH8, MH8	MH8, MH8	DP1DM5, DP1DM5, AIZU	DMOS6, MH8, MH8
Assembly Site	TAI	TAI	TAI	TAI
Package Group	SOIC	SOIC	SOIC	SOIC
Package Designator	DFM	DW	DW	DFM
Pin Count	20	16	16	20

QBS: Qual By Similarity, also known as Generic Data
Qual Device ISOW1044DFMR is qualified at MSL3 260C
Qual Device ISOW7741QDFMRQ1 is qualified at MSL3 260C

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: ISOW7741QDFMRQ1	QBS Process Reference: ISO7741FQDWQ1	QBS Package Reference: AMC1305M25QDWQ1	QBS Package Reference: AMC131M03QDFMRQ1
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	Pass	-	Pass	Pass
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	-
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	-	1/5/0	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	-
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	3/231/0	-	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	3/90/0	3/90/0	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	-	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/15/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	1/3/0	-	-

Type	#				Test Name	Condition				
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	1/6/0	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	3/90/0	-	-

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2312-048

Group 2 & 3
Qualification Report
Approve Date 15-FEBRUARY -2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Package Reference: MC33063ADR	QBS Package Reference: XMSM0L1306SDGS28R	QBS Package Reference: TMUX1134PWR	QBS Package Reference: TPS51916RUKR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	-	-	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	2/154/0	-	3/231/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	1/22/0	1/22/0	
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2602-072

Qualification Report
Approve Date 15-FEBRUARY -2026

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	QBS Package Reference: INA849DR	QBS Package Reference: SRC4190IDB	QBS Package Reference: TLC6946DBQR	QBS Package Reference: LM2594HVN-ADJ/NOPB	QBS Package Reference: TPD3S714QDBQRQ1	QBS Package Reference: TMUX1134PWR	QBS Package Reference: TRF7970AIRHBR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	3/231/0	3/231/0
HAST	A2	Temperature Humidity Bias	85C/85%RH	1000 Hours	3/231/0	-	-	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	3/231/0	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	-	3/231/0	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	3/231/0	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	3/231/0	3/231/0	-	3/231/0	-	-	-
HTOL	B1	Life Test	100C	300 Hours	1/77/0	-	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-	3/231/0	3/231/0
HTOL	B1	Life Test	150C	408 Hours	-	-	-	-	3/231/0	-	-
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	-	-	-	3/228/0	-	-	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	-	-	-	3/228/0	3/228/0	-	-
SD	C3	PB Solderability	Post 8hr steam	-	-	-	-	-	3/45/0	-	-
SD	C3	PB-Free Solderability	Post 8hr steam	-	-	-	-	-	3/45/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	1/22/0	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	-	3/15/0	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	1/30/0	-	3/90/0	1/30/0	-	1/30/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	3/90/0	1/30/0	-	1/30/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	-	-

QBS: Qual By Similarity, also known as Generic Data
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2602-071

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated

environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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